



100% Material Declaration Data Sheet for VOG20

PK131 (v1.3) Apr 22, 2016

Average Weight : 0.086000 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight	Component % of total
Die					0.004016	4.67%
	Silicon (Si)	7440-21-3	100.00	Silicon IC	0.004016	
Die Attach					0.000714	0.83%
	gamma-butyrolactone	96-48-0	3.00	Attach	0.000021	
	Phenol-formaldehyde polymer	9003-35-4	3.00	Attach	0.000021	
	Phenolic epoxy resin F-44	9003-36-5	22.00	Attach	0.000157	
	silver	7440-22-4	72.00	Attach	0.000514	
Bonding Wire					0.000172	0.20%
	Gold (Au)	7440-57-5	100.00	Wire	0.000172	
Molding Compound					0.056622	65.84%
	4,4'-Dihydroxy-3,3',5,5'-tetramethyldiphenylmethane diglycidyl ether	93705-66-9	8.00	Encapsulation	0.004530	
	aluminium hydroxide	21645-51-2	3.00	Encapsulation	0.001699	
	Benzaldehyde, hydroxy-, polymer with phenol	106466-55-1	5.00	Encapsulation	0.002831	
	Carbon black	1333-86-4	1.00	Encapsulation	0.000566	
	Silica, vitreous	60676-86-0	83.00	Encapsulation	0.046997	
Ext. Plating					0.000198	0.23%
	Tin (Sn)	7440-31-5	100.00	Base metal	0.000198	
Lead-frame alloy					0.023676	27.53%
	Copper (Cu)	7440-50-8	97.40	Base metal	0.023060	
	Iron (Fe)	7439-89-6	2.30	Base metal	0.000545	
	Phosphorus	7723-14-0	0.10	Base metal	0.000024	
	Zinc (Zn)	7440-66-6	0.20	Base metal	0.000047	
Leadframe Plating					0.000602	0.70%
	Silver	7440-22-4	100.00	Base metal	0.000602	

Revision History

Date	Version	Description of Revisions
3/21/2006	1.0	Initial Xilinx release
07/10/2006	1.1	100% Material Declaration
9/29/2006	1.2	Updated component descriptions
04/22/2016	1.3	Update mold compound & silver epoxy material

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